# PATENT COOPERATION TREATY

# PCT

	REC'D	2 2	MAR	2006
I	<b>WIPO</b>			D.O.

# INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

(Chapter II of the Patent Cooperation Treaty) (PCT Article 36 and Rule 70)

Applicant's or agent's file reference 10012333W001	FOR FURTHER AC	TION	See Form PCT/IPEA/416		
International application No. PCT/JP2004/019486	International filing date (a 20.12		Priority date (day/month/year) 22.12.2003		
B05D5/12(2006.01), Н	05C5/00(2006.01	), B05C11/10(2	2006.01), B05D1/26(2006.01),		
Applicant CANON KABUSHIKI KA	ISHA				
Authority under Article 35 and tra  2. This REPORT consists of a total of 3. This report is also accompanied by a. a total of 5  sheets of the description	nsmitted to the applican of 3 sheets, y ANNEXES, comprising sheets, as follows: cription, claims and/or distaining rectifications au	t according to Article Sincluding this cover sag:			
sheets which supersede earlier sheets, but which this Authority considers contain an amendment that goes beyond the disclosure in the international application as filed, as indicated in item 4 of Box No. I and the Supplemental Box.					
b. a total of (indicate type and number of electronic carrier(s))  containing a sequence listing and/or tables related thereto, in electronic form only, as indicated in the Supplemental Box Relating to Sequence Listing (see Section 802 of the Administrative Instructions).					
4. This report contains indications re	4. This report contains indications relating to the following items:				
Box No. I Basis of the	report				
Box No. II Priority					
Box No. III Non-establis	Box No. III Non-establishment of opinion with regard to novelty, inventive step and industrial applicability				
Box No. IV Lack of unity of invention					
Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement					
Box No. VI Certain docu		5 Such Sutcinoit			
Box No. VII Certain defe	cts in the international a	pplication			
Box No. VIII Certain obse	rvations on the internati	onal application			
Date of submission of the demand		Date of completion of this report			
		•			
13.10.2005			15.03.2006		
Name and mailing address of the IPEA/JP		Authorized officer	3S 9341		
Japan Patent Office	e	Kagami Nobu	hiro		
3-4-3, Kasumigaseki, Chiyoda-ku, Tokyo 100-8915, Japan		Telephone No. +81-3-3581-1101 Ext. 3391			

## INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

International application No.
PCT/JP2004/019486

Box No.	. I	Basis of the report				
1. W	the int a tran transl	ard to the language, this report is based on: nternational application in the language in which i inslation of the international application into slation furnished for the purposes of: international search (Rules 12.3(a) and 23.1(b)) publication of the international application (Rules international preliminary examination (Rules 55.	de 12.4(a))	, which is the language of a		
fur	rnished to	rd to the <b>elements</b> of the international applicat to the receiving Office in response to an invitatio of annexed to this report):				
	the in	nternational application as originally filed/furni	ished			
区	the de	escription:				
	pages	s <u>1-41</u>		as originally filed/furnished		
	pages*	5* r				
	pages*		received by this Authority on			
Ø	the cla					
	Nos.	5-6,8-11,16		as originally filed/furnished		
	Nos.*	*	as amended (together with a	any statement) under Article 19		
	Nos.* Nos.*		received by this Authority on 13.1			
3. d;			received by this Authority on			
l <b>⊻</b> she		awings: 1-21				
	<del>eets</del> /figs eets/figs *	*	received by this Authority on	as originally filed/furnished		
	eets/figs * eets/figs *		received by this Authority on received by this Authority on			
<b>-</b>	319/11 <sup>20</sup>	·	received by this Authority on			
	a sequ	uence listing and/or any related table(s) - see Su	upplemental Box Relating to Sequen	ce Listing.		
3. 🔽	The ar	The amendments have resulted in the cancellation of:				
		the description, pages				
		the claims, Nos. $2, 4, 7, 13-15, 17$	-19			
		the common listing ( ) (C)				
		any table(s) related to sequence listing (special				
4.	made, (Rule 7	This report has been established as if (some of) the amendments annexed to this report and listed below had not been made, since they have been considered to go beyond the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).				
	∏! t	the description, pages		<del></del>		
		Alexander and Art				
	[ t	41 1				
	[ t	the sequence listing (specify):				
	<u> </u>	any table(s) related to sequence listing (specify				
* If item	ı 4 applic	ies, some or all of those sheets may be marked "su	uperseded."			

#### INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

International application No.
PCT/JP2004/019486

Box No. V Reasoned statement us citations and explanations	Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; itations and explanations supporting such statement			
1. Statement				
Novelty (N)	Claims Claims	1,3,5-6,8-12,16	YES	
	Claims		NO	
Inventive step (IS)	Claims		YES	
	Claims	1,3,5-6,8-12,16	NO	
Industrial applicability (IA)	Claims	1,3,5-6,8-12,16	YES	
	Claims		NO	

- 2. Citations and explanations(Rule 70.7)
- D1:JP 11-274671 A(SEIKO EPSON CORPORATION) 1999.10.08(Family:None)
- D2:WO 2003/105547 A1(FUJI PHOTOFILM CO.,LTD.) 2003.12.18 & US 2003/228543 A1

Claims 1,3,5-6,8-12,16 do not involve inventive steps over D1 or D2. D1 or D2 discloses a wiring method of forming the first pattern and the second pattern on a substrate by supplying the first liquid and the second liquid to said each of the patterns independently. And it is a normal option for a person skilled in the art to decide the forming order of some patterns by considering the information of a wiring pattern.

#### CLAIMS

1. (Amended) A wiring forming method of supplying a first liquid and a second liquid in such a manner that said first liquid and said second liquid contact with each other on a substrate to thereby form a wiring pattern including the first pattern and the second pattern on the substrate, the method comprising:

a first pattern forming step of supplying the first liquid to thereby form the first pattern on the substrate; and

a second pattern forming step of supplying the second liquid to thereby form the second pattern on the substrate,

wherein a forming order of said first pattern and said second pattern for constituting said wiring pattern in a same layer is changed in accordance with information of said wiring pattern.

#### 2. (Cancelled)

20

5

10

3. (Amended) The wiring forming method according to claim 1, wherein curing process is performed each time said first pattern or said second pattern is formed to the substrate.

### 4. (Cancelled)

- 5. The wiring forming method according to claim 1, wherein the first pattern forming step comprises the steps of: forming the first patterns on a plurality of positions of the substrate, and thereafter the second pattern forming step comprises the steps of: forming the second pattern between the first patterns formed in the plurality of positions on the substrate in such a manner as to bring the second pattern into contact with the first pattern.
- 6. The wiring forming method according to claim 1, further comprising the steps of: discharging the first and second liquids by an ink jet system to thereby supply the liquids onto the substrate.

#### 7. (Cancelled)

8. The wiring forming method according to claim 1, wherein the first pattern is an insulated pattern

having an insulating property, and the second pattern is a conductive pattern having conductivity.

- The wiring forming method according to claim
   1, wherein the first and second patterns are insulating insulated patterns having different properties.
- The wiring forming method according to claim
   wherein the first pattern is an insulated pattern
   having an insulating property, and the second pattern
   a semiconductor pattern of a semiconductor.
- 11. A wiring board comprising: a wiring formed by the wiring forming method according to claim 1; and the substrate.
- 12. (Amended) A wiring forming apparatus for supplying a first liquid forming a first pattern and a second liquid forming a second pattern in such a manner that the first liquid and the second liquid contact with each other on a substrate to thereby form a wiring pattern including said first pattern and said second wiring pattern on the substrate, the apparatus comprising:
- a first liquid container which stores the first liquid;
  - a second liquid container which stores the second

## liquid;

5

first pattern forming means for supplying the first liquid on the substrate from the first liquid container to thereby form the first pattern;

second pattern forming means for supplying the second liquid on the substrate from the second liquid container to thereby form the second pattern; and

means for changing a forming order of said first pattern formed by using said first pattern forming

means and said second pattern formed by using said second forming means in accordance with information of said wiring pattern upon forming said wiring pattern in a same layer.

- 15 13. (Cancelled)
  - 14. (Cancelled)
  - 15. (Cancelled) ·

16. The wiring forming apparatus according to claim 12, wherein a size of the corresponding first pattern is changeable in accordance with that of the second pattern to be formed.

5

- 17. (Cancelled)
- 18. (Cancelled)
- 10 19. (Cancelled)